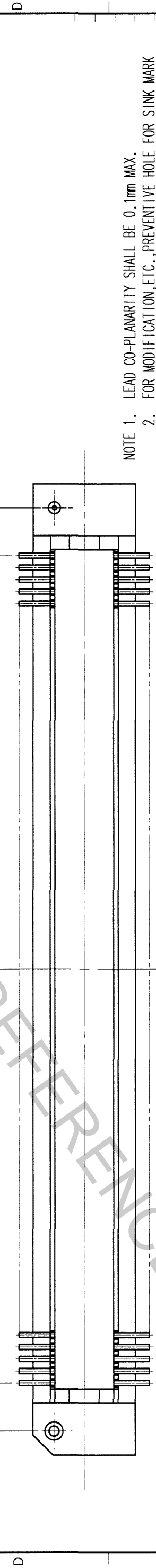
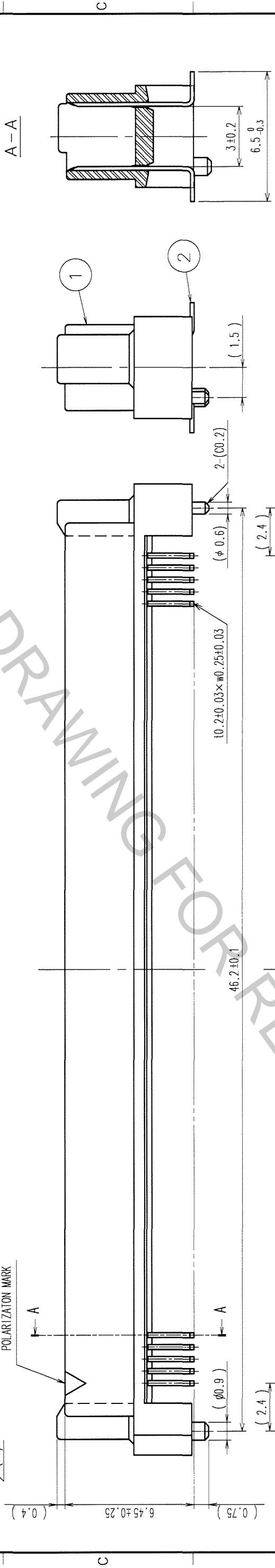
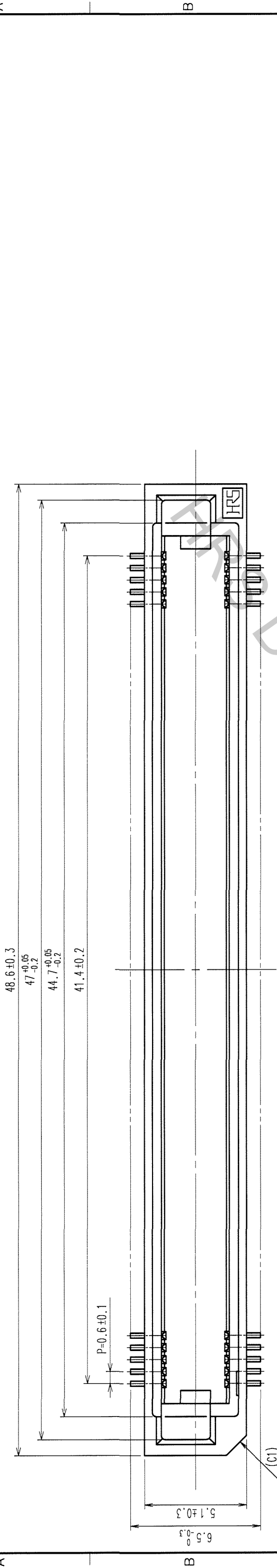


1		2		3		7		8	
COUNT		DESCRIPTION OF REVISIONS		DATE		BY		CHKD	

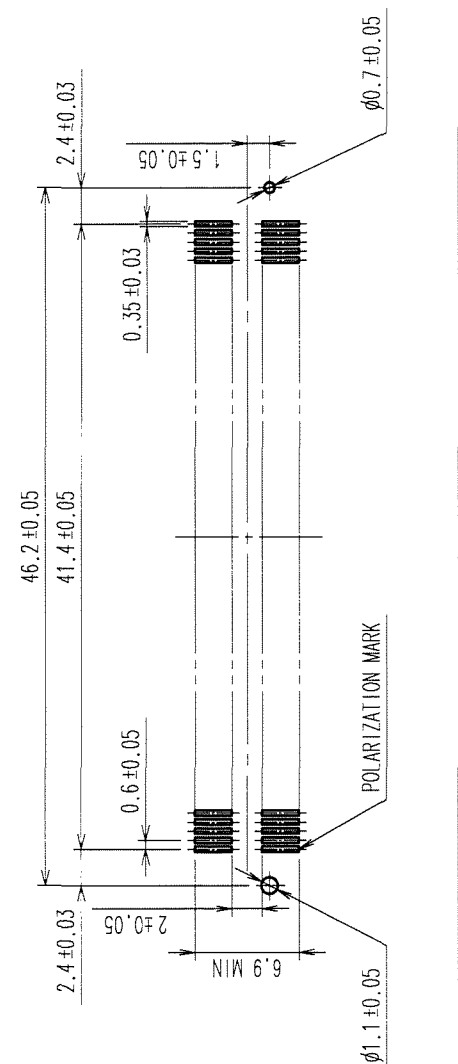
A

A



46.2 ±0.05		2.4 ±0.03		2.4 ±0.03		CONTACT AREA: GOLD 0.1 μ m min.	
41.4 ±0.05		0.6 ±0.05		0.35 ±0.03		LEAD AREA: TIN-PLATING 1 μ m min.	
2.4 ±0.03		2 ±0.05		1.5 ±0.05		UNDER PLATING: NICKEL 1 μ m min.	
6.9 MIN		POLARIZATION MARK		φ1.1 ±0.05			
φ0.7 ±0.05							

1	PPS	LIGHT BROWN (UL94V-0)	2	PHOSPHOR BRONZE	CONTACT AREA: GOLD 0.1 μ m min. LEAD AREA: TIN-PLATING 1 μ m min. UNDER PLATING: NICKEL 1 μ m min.
NO.	MATERIAL	FINISH, REMARKS	NO.	MATERIAL	FINISH, REMARKS
CODE NO. (OLD) CL			DRAWN K. NAKAMURA	DESIGNED K. NAKAMURA	CHECKED K. Ogawa
			05.11.17	05.11.17	05.11.17
DRAWING NO. EDC3-150845-25		PART NO. FX8C-140P-SV2 (71)		RELEASED	
SCALE 5 : 1					
UNITS mm					
HIROSE ELECTRIC CO., LTD.		CODE NO. CL578-0547-0-71		1 / 1	



NOTE 1. LEAD CO-PLANARITY SHALL BE 0.1mm MAX.
2. FOR MODIFICATION, ETC., PREVENTIVE HOLE FOR SINK MARK MAY BE ADDED ACCORDING TO CIRCUMSTANCES.
3. THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCE.

RECOMMENDED LAND PATTERN DIMENSION OF PCB (MOUNTING SIDE) (2:1)

TO
PCK